

TN00036

USB D Library for LPC1100 series MCUs

1.0 — 13 March 2018

Technical note

Document information

Info	Content
Keywords	USB D library source code, LPC, USB stack.
Abstract	This technical note describes the history of USB D ROM device driver stack and releases the latest USB D library source with bug fixes and new features. The latest USB D library supports most of the LPC family MCUs including LPC1100 series, LPC1500 series, and LPC54000 series. USB D device driver stack for LPC1800 and LPC4300 series is not included here and will be provided as a separate package.



Revision history

Rev	Date	Description
1.0	20180314	Initial version.

Contact information

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1. Introduction

ROM-based USB driver is provided as part of the boot ROM since LPC1100 series USB based MCUs are widely implemented.

The ROM contains flexible USB device stack to simplify the USB application development. The USB ROM stack has built-in support for Communication Device Class (CDC), the Human Interface Device (HID), the Mass Storage Class (MSC), and the Device Firmware Upgrade (DFU) class. It also supports composite device model consisting of multiple interfaces of these supported classes.

However, there are limitations in the earlier version of the USB driver and few known issues identified over time by both NXP and end users. NXP is unable to provide instant ROM update for every USB driver issue found, therefore, errata sheets with work-arounds are offered where possible. On the other hand, hardware features, such as Link Power Management (LPM) were not supported in the earlier version of the USB ROM, therefore no work-around is available.

The ROM based USB driver simplifies the USB application development, however, it makes debugging of complex USB class driver more difficult. In addition, some USB ROM work-arounds require more RAM resources.

On MCUs with larger flash memory size, linking the USB library components directly speed up development and make debugging easier. All these work-arounds can then be removed.

NXP now publishes two versions of the USB driver stack source code: one residing in the MCU ROM as the reference and the updated version, also known as the USB library, with bug fixes on all known issues and additional new features. Some of the key new features of the USB library include:

- Link Power Management (LPM) Support.
- Root 2 test support.
- Enhancement to DFU class to support multiple alternate interfaces.
- String descriptor callback. New stack has callback to provide customer string descriptors not present in descriptor array for random indexed strings.

This technical note gives an overview of how to use the USB library to build a USB application.

At an early stage of the USB controller integration, Keil and NXP collaborated to provide USB driver software support solution. Later, NXP added more low-level drivers to support different USB IPs, new features such as Link Power Management (LPM) support, more USB class, such as DFU class driver support, improved memory management and included callbacks to make the USB stack more user friendly with regular bug fixes.

The following is the original Copyright statement of USB driver examples from Keil:

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2. Description

Error! Reference source not found. Fig 1 shows the architectural block diagram of the USB device ROM stack. The stack consists of three main layers:

1. The Class Layer
2. The USB Core Layer
3. The Device Controller Driver Layer

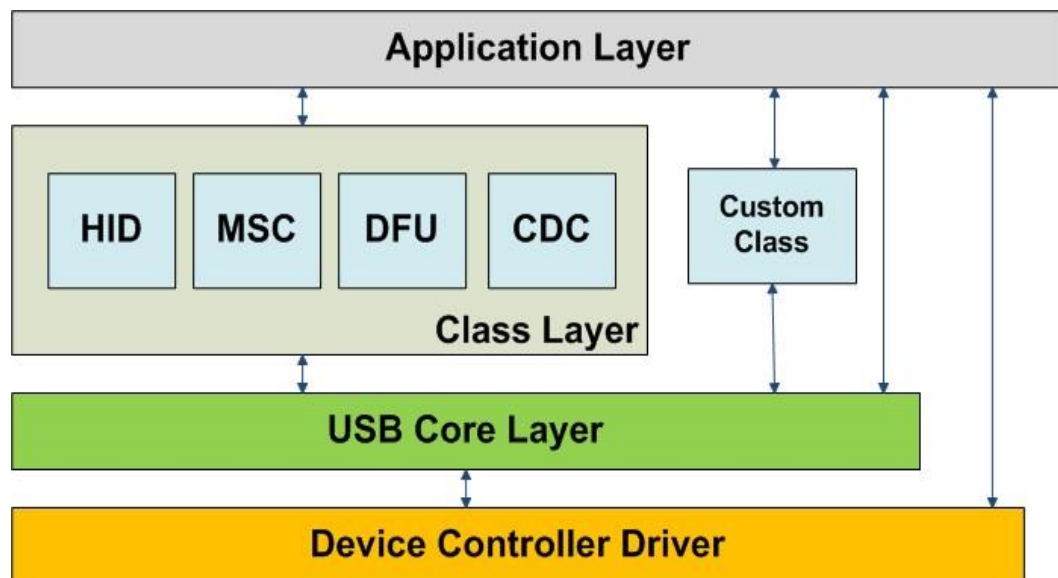


Fig 1. USB device ROM stack block diagram

The source files of the updated USB library are built and tested on Keil, IAR, and MCUXpresso IDEs.

The LPCXpresso Development Board for LPC11U68 MCUs is used in this technical note. For details of the board, see:

<https://www.nxp.com/support/developer-resources/hardware-development-tools/lpcxpresso-boards/lpcxpresso-board-for-lpc11u68:OM13058>

The attached USB library package is based on LPCOpen (version 3) for LPC11U68:

“usbd_rom_lpc11u68” directory contains the source of original USB stack residing in the ROM. **Since it is unmodified from the LPC11U6x ROM, it contains all the known issues of the USB ROM device driver stack listed in the LPC11U68 Errata and should be used as reference only.**

Note: For the ROM release, the source files of the USB ROM driver were built on the Keil MDK only. Some of the directives and keywords in the source are for Keil compiler only and may not work on other compilers.

“usbd_lib_lpc11u68” directory contains the latest USB stack library with fixes of all known issues from USB ROM. It also contains the LPCOpen.USB examples using USB library API calls.

Under “usbd_lib_lpc11u68” directory, “LPC_USBD_Lib” contains the latest USB stack library and USB examples utilizing the USB library. Identical LPCOpen (version 3) directory structure is applied to these USB examples.

The example is available in three tool chains:

- IAR embedded Workbench
- Keil MDK
- MCUXpresso

The USB library can be found under:

\\usbd_lib_lpc11u6x\prj_lpc_usbd_lib

The USB class examples can be found under:

\\usbd_lib_lpc11u6x\prj_xpresso11u68

The USB library documentation (revision 2.0) in HTML format is under:

\\usbd_lib_lpc11u6x\LPC_USBD_Lib\docs\html

Click **\\usbd_lib_lpc11u6x\LPC_USBD_Lib\docs\html\index.html** to start.

If using Internet Explorer, click “Allow block Content” to allow page to run script and active X control.

It is important to note that there are differences between the library documentation and the Section “USB ROM API” of the User Manual. The key difference is related to USB_API_INIT_PARAM data structure defined in “chip_11u6x\usbd_lib” directory where all the new features have been added.

Under “LPC_USBD_Lib\mw_usbd” directory, mw_usbd_rom.c has the version identifier of the latest USB library stack.

Following the “LPCOpen Quick Start Guide for all platforms”, build chip and board libraries first under “lib_chip_lpcxxx” and “lib_board_lpcxxx”, then, build USB library under “LPC_USBD_Lib”, finally, build the USB class application under “prj_xpresso11u68” directory.

Now, the USB class application links the USBD library APIs instead of the USBD ROM APIs and is ready to run.

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